

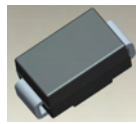
**1.5A SURFACE MOUNT FAST RECOVERY RECTIFIER**

**Features**

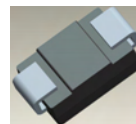
- Glass Passivated Die Construction
- Fast Recovery Time For High Efficiency
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

**Mechanical Data**

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 
- Polarity: Cathode Band or Cathode Notch
- SMA Weight: 0.065 grams (approximate)
- SMB Weight: 0.09 grams (approximate)



Top View



Bottom View

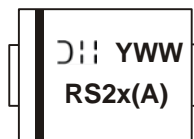
**Ordering Information** (Note 3)

Part Number	Case	Packaging
RS2xA-13-F	SMA	5000/Tape & Reel
RS2x-13-F	SMB	3000/Tape & Reel

\*x = Device type, e.g. RS2DA-13-F (SMA package); RS2J-13-F (SMB package).

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
  2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
  3. For packaging details, go to our website at <http://www.diodes.com>.

**Marking Information**



RS2x = Product type marking code, ex: RS2G (SMB package)  
 RS2xA = Product type marking code, ex: RS2GA (SMA package)  
 DII = Manufacturers' code marking  
 YWW = Date code marking  
 Y = Last digit of year (ex: 2 for 2002)  
 WW = Week code (01 to 53)

### Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitance load, derate current by 20%.

Characteristic	Symbol	RS2 A/AA	RS2 B/BA	RS2 D/DA	RS2 G/GA	RS2 J/JA	RS2 K/KA	RS2 M/MA	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	$V_{RWM}$								
DC Blocking Voltage (Note 4)	$V_R$								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_T = 120^\circ\text{C}$	$I_O$	1.5							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	50							A

### Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 5)	$R_{\theta JT}$	20	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

### Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	RS2 A/AA	RS2 B/BA	RS2 D/DA	RS2 G/GA	RS2 J/JA	RS2 K/KA	RS2 M/MA	Unit
Forward Voltage @ $I_F = 1.5\text{A}$	$V_{FM}$	1.3							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage (Note 4) @ $T_A = 125^\circ\text{C}$	$I_{RM}$	5.0 200							$\mu\text{A}$
Reverse Recovery Time (Note 6)	$t_{rr}$	150			250	500		ns	
Typical Total Capacitance (Note 7)	$C_T$	30							pF

- Notes:
- Short duration pulse test used to minimize self-heating effect.
  - Reverse recovery test conditions:  $I_F = 0.5\text{A}$ ,  $I_R = 1.0\text{A}$ ,  $I_{rr} = 0.25\text{A}$ . See Figure 5.
  - Thermal Resistance: Junction to terminal, unit mounted on PC board with  $5.0\text{ mm}^2$  ( $0.013\text{ mm}$  thick) copper pads as heat sink.
  - Measured at  $1.0\text{MHz}$  and applied reverse voltage of  $4.0\text{V DC}$ .

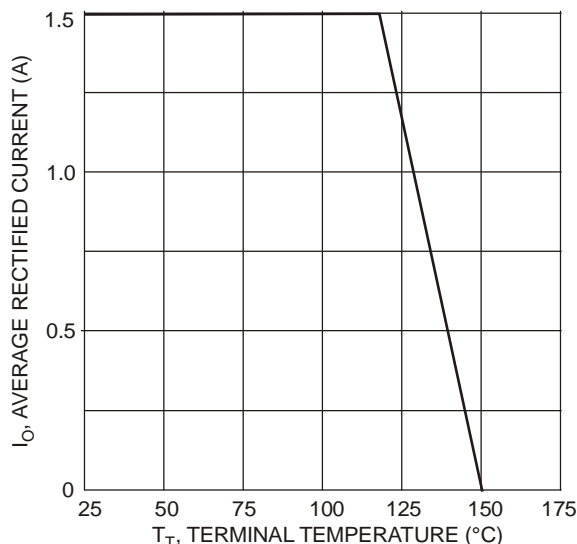


Fig. 1 Forward Current Derating Curve

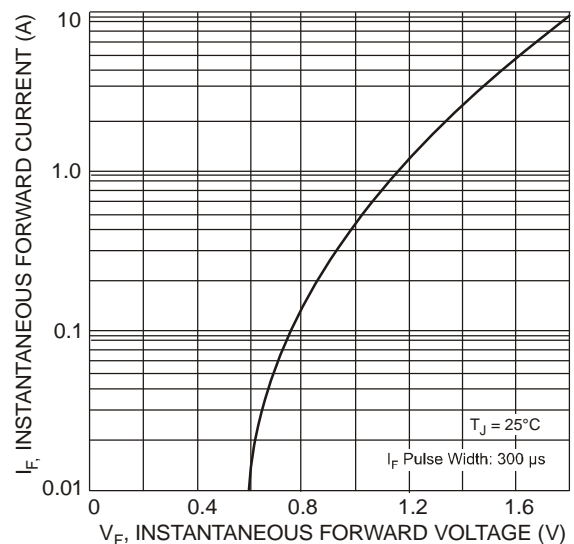


Fig. 2 Typical Forward Characteristics



Fig. 3 Forward Surge Current Derating Curve

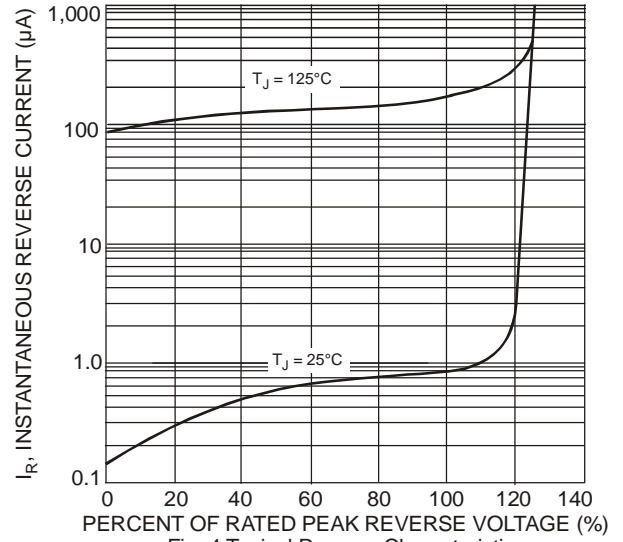
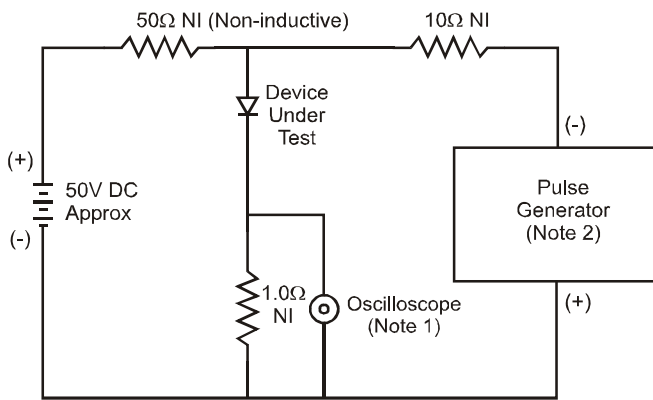
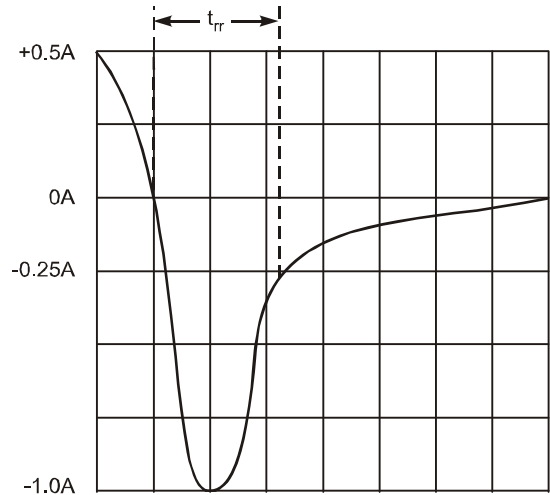


Fig. 4 Typical Reverse Characteristics



- Notes:  
 1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.  
 2. Rise Time = 10ns max. Input Impedance = 50Ω.



Set time base for 50/100 ns/cm

Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

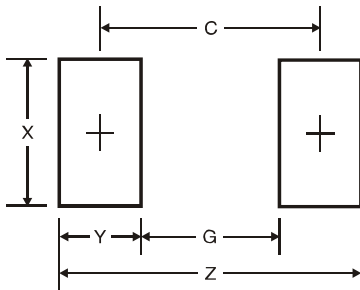
**Package Outline Dimensions**



SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

## Suggested Pad Layout



SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
X	1.7
Y	2.5
C	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

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